

SOLDER CONNECTION

Email: sales@solderconnection.co.uk | Tel: +44(0)1291 624 400

QUALITEK® Technical Bulletin

Delta WS700 60/40 Water Soluble Solder Wire

DESCRIPTION

WS700 is a Sn60/Pb40 water soluble cored solder wire designed for electronic applications. WS700 has rapid wetting action and flux residues are easily removed with water rinse or in-line cleaning systems. WS700 cored solder wire will not decompose or carbonize under prolonged heat. WS700 meets IPC-J-STD-004B specifications.

FEATURES AND BENEFITS

- Rapid wetting action
- Residues easily removed with water

FEATURES AND BENEFITS

Colour & Appearance	Specification	Test Method
Flux Classification	Lt. Opaque Solid	Visual
Copper Mirror	ORH1	J-STD-004
Corrosion	Complete removal of copper film	IPC-TM-650 2.3.32
SIR	Pass (cleaned coupons)	IPC-TM-650 2.6.15
Post Reflow Flux Residue	$>1.0 \times 10^8$ ohms	IPC-TM-650 2.6.3.3
Acid Value	65%	TGA Analysis IPC-
Solder Spread	160 - 180	TM-650 2.3.13 IPC-
	180 mm ²	TM-650 2.4.46

WIRE DIAMETER

Delta Solder Wire WS700 60/40 is available in a variety of diameters. The chosen diameter is based on application methods, pad size, and desired solder joint volume. Generally, the diameter of the wire should be slightly larger than the width/diameter of the joint or connection to be soldered. Below is a list of standard diameters.

Diameter/Inch	0.125	0.092	0.062	0.050	0.040	0.032	0.028	0.025	0.020	0.015
Diameter/mm	3.18	2.33	1.57	1.27	1.01	0.81	0.71	0.63	0.51	0.38
Std. Wire	11	13	16	18	19	21	22	23	25	28
Gauge										
Tolerance, in.	+/-0.006	+/-0.005	+/-0.003	+/-0.003	+/-0.002	+/-0.002	+/-0.002	+/-0.002	+/-0.002	+/-0.002

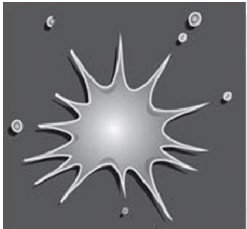
FLUX PERCENTAGE

Utilizes a state-of-the-art automatic wire extrusion and wire drawing machines to manufacture consistent solder. The introduction of flux core in the wire extrusion process involves continual monitoring of flux percentage to ensure minimal flux voids and irregular wire. Typical flux percentage for leaded solder is 1.1 – 3.3%.

PHYSICAL PROPERTIES

A no clean resin based core flux with alloy composition Sn60/Pb40, which is a eutectic alloy. 60/40 alloys conform to and exceed the impurity requirements of IPC-J-STD-006C.

Issue 1 - 25/02/20



SOLDER CONNECTION

Email: sales@solderconnection.co.uk | Tel: +44(0)1291 624 400

TYPICAL ANALYSIS

Typical Analysis													
Sn	Ag	Cu	Pb	Sb	Bi	In	As	Fe	Ni	Cd	Al	Zn	Au
59.5 -60.5	0.100 Max	0.080 Max	Bal	0.200 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max

	Sn60/Pb40
Melting Point, °C	183 - 188
Hardness, Brinell	16 HB
Coefficient of Thermal Expansion	23.9
Tensile Strength, kgf/cm ²	535
Tensile Elongation, %	40
Density, g/cm ³	8.50
Electrical Resistivity, (μΩ-cm)	15.3
Thermal Conductivity, W/m-K	49

FLUX RESIDUES & CLEANING

WS700 is a water-soluble formulation; therefore, the residues need to be removed. Residue removal is easily achieved, with the use of hot 60 °C (140 °F) de-ionized water in either a batch or conveyor cleaner system

STORAGE & SHELF LIFE

Solder wire storage should be in a 65-80 °F environment away from direct heat. We recommend using gloves when handling solder wire directly. Solder wire has an indefinite shelf life.

DISPOSAL

WS700 60/40 solder should be disposed of in accordance with federal, state & local authority requirements.

The information contained herein is based on data considered accurate and is offered at no charge. No warranty is expressed or implied regarding the accuracy of this data. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of the materials designated.